

March 2008

FST3345 — 8-Bit Bus Switch

Features

- 4Ω Switch Connection between Two Ports
- Minimal Propagation Delay through the Switch
- Low I_{CC}
- Zero Bounce in Flow-through Mode
- Control Inputs Compatible with TTL Level

Description

The FST3345 switch provides eight-bits of high-speed CMOS TTL-compatible bus switching. The low on resistance of the switch allows inputs to be connected to outputs without adding propagation delay or generating additional ground bounce noise.

The device is organized as an eight-bit switch with dual output enable inputs (OE and /OE). When /OE is LOW or OE is HIGH, the switch is ON and port A is connected to port B. When /OE is HIGH, and OE is LOW, the switch is OPEN and a high-impedance state exists between the two ports.

Ordering Information

Part Number	Operating Temperature Range		Packing Method
FST3345WMX	-40 to +85°C	20-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300-inch Wide	Tape and Reel
FST3345QSC	-40 to +85°C	20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide	Tube
FST3345QSCX	-40 to +85°C	20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide	Tape and Reel
FST3345MTC	-40 to +85°C	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tube
FST3345MTCX	-40 to +85°C	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tape and Reel

All packages are lead free per JEDEC: J-STD-020B standard.

The Fairchild switch family derives from and embodies Fairchild's proven switch technology used for several years in its 74LVX3L384 (FST3384) bus switch product.

Logic Diagram

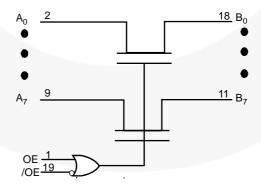
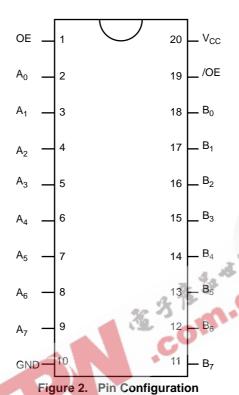


Figure 1. Logic Diagram

Pin Configuration



Pin Descriptions

Pin #	Pin Names	Description	
1,19	OE, /OE	Bus Switch Enables	
2,3,4,5,6,7,8,9	$A_0, A_1, A_2, A_3, A_4, A_5, A_6, A_7$	Bus A	
10	GND	Ground	
11,12,13,14,15,16,17,18	B ₇ ,B ₆ ,B ₅ ,B ₄ ,B ₃ ,B ₂ ,B ₁ ,B ₀	Bus B	
20	Vcc	Supply Voltage	

Truth Table

1	nput	Function
OE	/OE	Function
Don't Care	LOW	Connect
HIGH	Don't Care	Connect
LOW	HIGH	Disconnect

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage	-0.5	7.0	V
Vs	DC Switch Voltage	-0.5	7.0	V
V _{IN}	DC Input Voltage ⁽¹⁾	-0.5	7.0	V
I _{IK}	DC Input Diode Current, V _{IN} < 0V		-50	mA
I _{OUT}	DC Output Sink Current		128	mA
I _{CC} / I _{GND}	DC V _{CC} / GND Current		±100	mA
T _{STG}	Storage Temperature Range	-65	+150	°C

Note:

The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

逐为海海水果 The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter		Min.	Max.	Unit
Vcc	Power Supply Operating		4.0	5.5	V
V_{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	5.5	V
4 4.	to the least Discount Fall Time	Switch Control Input ⁽²⁾	0	5	ns/V
t _r , t _f Input Rise	Input Rise and Fall Time	Switch I/O		DC	115/ V
T _A	Operating Temperature, Free Air		-40	+85	°C

Note:

2. Unused control inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Typical values are at $V_{CC} = 5.0V$ and $T_A = 25$ °C.

Symbol	Dorometer	Conditions	V _{cc} (V)	T _A =-40 to +85°C			I linita
Symbol	Parameter	Conditions V _{cc}		Min.	Тур.	Max.	Units
V _{IK}	Clamp Diode Voltage	I _{IN} = -18mA	4.5			-1.2	V
V _{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V _{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
I _{IN}	Input Leakage Current	$0 \leq V_{IN} \leq 5.5 V$	5.5			±1.0	μA
l _{oz}	Off-state Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μA
		$V_{IN} = 0V$, $I_{IN} = 64mA$	4.5		4	7	
В	Switch On Resistance ⁽³⁾	$V_{IN} = 0V$, $I_{IN} = 30mA$	4.5		4	7	Ω
R _{ON}	Switch On Resistance	$V_{IN} = 2.4V, I_{IN} = 15mA$	4.5		8	15	1 12
		$V_{IN} = 2.4V, I_{IN} = 15mA$	4.0		11	20	
Icc	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	5.5	8		3	μA
Δlcc	Increase in I _{CC} per Input	One Input at 3.4V, Other Inputs at V _{CC} or GND	5.5	CI		2.5	mA

Note:

3. Measured by the voltage drop between the A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the A or B pins.

AC Electrical Characteristics

 $T_A = -40 \text{ to } +85^{\circ}\text{C}, \ C_L = 50 \text{pF}, \ \text{and} \ R_U = R_D = 500 \Omega.$

Symbol	Parameter	Conditions	$V_{CC} = 4.5$	5 – 5.5V	V _{CC} =	4.0V	Units	Figure
Symbol	Farameter	Conditions	Min.	Max.	Min.	Max.	Offics	rigure
t _{PHL} , t _{PLH}	Propagation Delay Bus-to-Bus ⁽⁴⁾	V _{IN} = Open		0.25		0.25	ns	Figure 3 Figure 4
t _{PZH} ,t _{PZL}	Output Enable Time	$V_{IN} = 7V$ for t_{PZL} $V_{IN} = 0$ pen for t_{PZH}	1.5	6.5		7.0	ns	Figure 3 Figure 4
t _{PHZ} , t _{PLZ}	Output Disable Time	$V_{IN} = 7V$ for t_{PLZ} $V_{IN} = 0$ for t_{PHZ}	1.0	8.0		8.2	ns	Figure 3 Figure 4

Note:

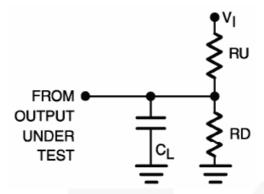
4. This parameter is guaranteed by design, but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical on resistance of the switch and the 50pF load capacitance when driven by an ideal voltage source (zero output impedance).

Capacitance

 $T_A = +25$ °C, f = 1MHz. Capacitance is characterized, but not tested.

Symbol	Parameter	Conditions	Тур.	Units
C _{IN}	Control Pin Input Capacitance	V _{CC} = 5.0V	4	pF
C _{I/O}	Input/Output Capacitance	V _{CC} , /OE = 5.0V, OE = 0V	5	pF

AC Loadings and Waveforms



Notes: Input driven by 50Ω source terminated in 50Ω . C_L includes load and stray capacitance. Input PRR = 1.0MHz, t_w = 500ns.

Figure 3. AC Test Circuit

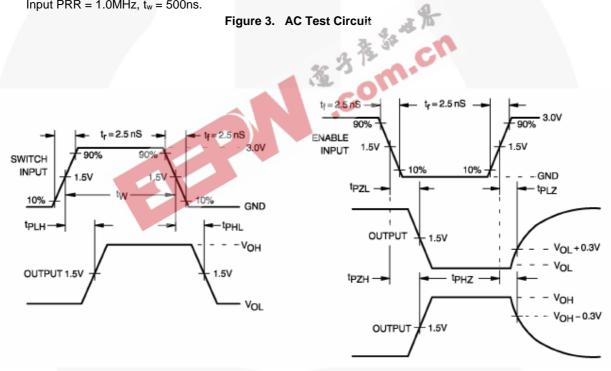


Figure 4. AC Waveforms

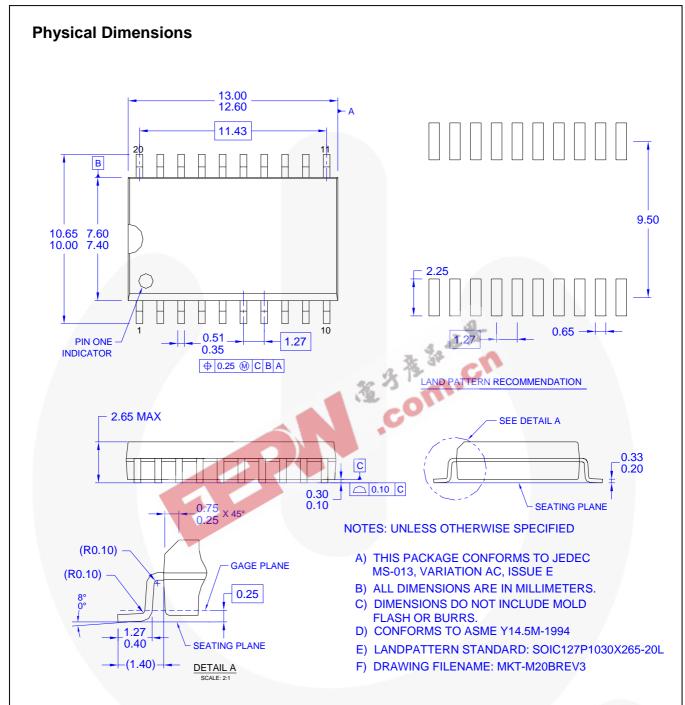


Figure 5. 20-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300-inch Wide

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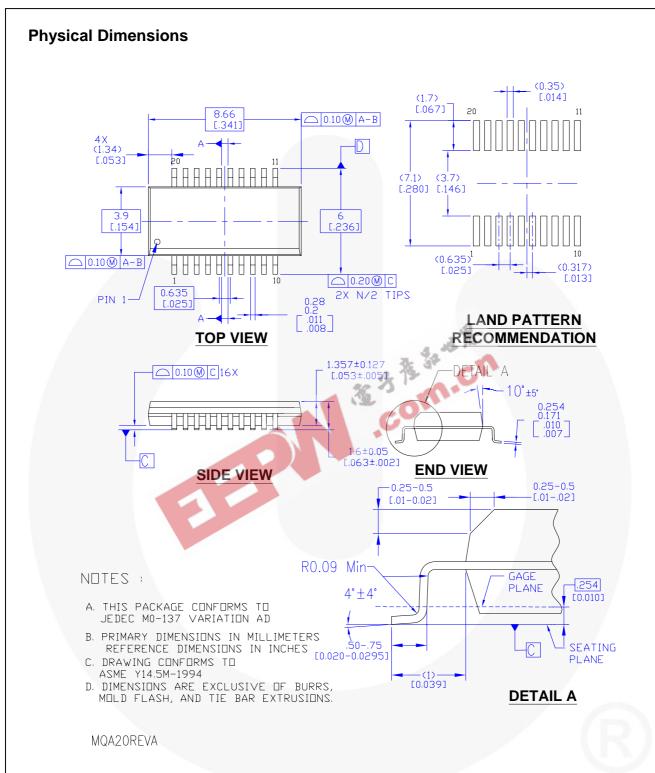


Figure 6. 20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide

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Physical Dimensions -0.20 120 4.16 6,4 4.4±0.1 -B-3,2 0.42 0.2 C B A ALL LEAD TIPS PIN #1 IDENT. PATTERN RECOMMENDATION D.1 C -C-0.09-0.20 0.1±0.05 0.65 -12.00° R0.09min GAGE PLANE DIMENSIONS ARE IN MILLIMETERS 0.25 SEATING PLANE NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE $7/93.\,$ -0.6±0.1-R0.09min -1.00 B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS. DETAIL A D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

Figure 7. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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